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TECHNOLOGY CENTER

1. (Amended) A semiconductor device comprising a first semiconductor chip and a second semiconductor chip superposed on and bonded to a surface of the first semiconductor chip,

wherein, in a region on the surface of the first semiconductor chip where the second semiconductor chip is bonded to the first semiconductor chip, chip connection portions are arranged in standardized positions so as to fit a plurality of predetermined types of semiconductor chips, [and]

wherein, on the second semiconductor chip, chip connection portions are arranged [in standardized positions] so as to fit the chip connection portions arranged on the first semiconductor chip at least for one of the plurality of predetermined types of semiconductor chips, and

wherein at least part of the chip connection portions arranged on the first semiconductor chip are common to the plurality of predetermined types of semiconductor chips so as to be used for input/output of signals having identical specifications.

3. (Amended) A semiconductor chip having, on a surface thereof, a chip bonding region that fits one of a plurality of predetermined types of semiconductor chips,

wherein, in the chip bonding region, chip connection portions are arranged in standardized positions so as to fit any of the plurality of predetermined types of semiconductor chips, and

wherein at least part of the chip connection portions are common to the plurality of predetermined types of semiconductor chips so as to be used for input/output of signals having identical specifications.

10. (Amended) A semiconductor chip having, on a surface thereof, a chip connection region that fits any of a plurality of predetermined types of semiconductor chips,

wherein, in the chip connection region, chip connection portions are formed in standardized positions so as to fit any of the plurality of predetermined types of semiconductor chips, and the chip connection portions are arranged along an edge of the chip connection region, and

wherein at least part of the chip connection portions are common to the plurality of predetermined types of semiconductor chips so as to be used for input/output of signals having identical specifications.